# PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1
Stylesheet Version v1.2

EPAS ID: PAT5797048

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| **SUBMISSION TYPE:** | NEW ASSIGNMENT |
| **NATURE OF CONVEYANCE:** | ASSIGNMENT |

## CONVEYING PARTY DATA

| Name | Execution Date |
|---|---|
| RAMASAMY CHOCKALINGAM | 10/30/2019 |
| JUAN BOON TAN | 10/31/2019 |
| CHEE KONG LEONG | 10/29/2019 |
| RANJAN RAJOO | 10/25/2019 |
| XUESONG RAO | 10/29/2019 |
| XIAODONG LI | 10/31/2019 |

## RECEIVING PARTY DATA

| | |
|---|---|
| **Name:** | GLOBALFOUNDRIES SINGAPORE PTE. LTD. |
| **Street Address:** | 60 WOODLANDS INDUSTRIAL PARK D STREET 2 |
| **City:** | SINGAPORE |
| **State/Country:** | SINGAPORE |
| **Postal Code:** | 738406 |

## PROPERTY NUMBERS Total: 1

| Property Type | Number |
|---|---|
| **Application Number:** | 16669531 |

## CORRESPONDENCE DATA

**Fax Number:**

***Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.***

| | |
|---|---|
| **Phone:** | 518-305-9166 |
| **Email:** | ippg.prosecution@globalfoundries.com |
| **Correspondent Name:** | GLOBALFOUNDRIES, INC. |
| **Address Line 1:** | SANTA CLARA GATEWAY |
| **Address Line 2:** | 2600 GREAT AMERICA WAY |
| **Address Line 4:** | SANTA CLARA, CALIFORNIA 95054 |

| | |
|---|---|
| **ATTORNEY DOCKET NUMBER:** | LSG034-US-NP |
| **NAME OF SUBMITTER:** | DAVID CAIN |
| **SIGNATURE:** | /David Cain/ |
| **DATE SIGNED:** | 10/31/2019 |
| | This document serves as an Oath/Declaration (37 CFR 1.63). |

**Total Attachments: 6**

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GF Ref. No.: LSG034-US-NP

## COMBINED DECLARATION and ASSIGNMENT (37 CFR 1.63) FOR UTILITY OR DESIGN APPLICATION USING AN APPLICATION DATA SHEET (37 CFR 1.76)

| | |
|---|---|
| **Title of Invention** | **BOND PADS OF SEMICONDUCTOR DEVICES** |

### DECLARATION

As the below named inventor, I hereby declare that:

This declaration is directed to:

☒ The attached application, or

☐ United States application or PCT international application number __________ filed on __________

The above-identified application was made or authorized to be made by me.

I believe that I am the original inventor or an original joint inventor of a claimed invention in the application.

I hereby acknowledge that any willful false statement made in this declaration is punishable under 18 U.S.C. 1001 by fine or imprisonment of not more than five (5) years, or both.

I have reviewed and understand the contents of the application and am aware of the duty to disclose to the US Patent and Trademark Office all information known to me to be material to patentability as defined in 37 CFR § 1.56.

### ASSIGNMENT

For good and valuable consideration, the receipt, sufficiency and adequacy of which are hereby acknowledged, I hereby sell, assign, transfer, to GLOBALFOUNDRIES Singapore Pte. Ltd. having a business address of 60 Woodlands Industrial Park D Street 2, Singapore, 738406, its successors and assigns, absolutely and forever, my entire right, title and interest in and to the invention listed above, together with the Application, any and all Patents that may issue in the United States and/or any foreign countries, and any reissues, re-examinations, renewals, continuations, continuation-in-parts, divisionals or extensions thereof that may be issued or granted, and all right, title and interest to the inventions contained in said Patents and Applications, for the United States and all foreign countries, and all the rights and privileges relating thereto including but not limited to the priority rights arising from said Applications, the right to recover and take all such proceedings as may be necessary for the recovery of damages or otherwise in respect of past, present and future infringement, and the right to apply for, take and maintain patents on said inventions.

**If any portion of this Combined Declaration or Assignment is held unenforceable, then remaining portions hereof shall nevertheless remain in full force and effect.**

LEGAL NAME OF INVENTOR

Inventor: **CHOCKALINGAM, RAMASAMY** Date: 30-Oct-2019

Signature: C. Ramasamy

**Note: An application data sheet (PTO/SB/14 or equivalent), including naming the entire inventive entity, must accompany this form. Use an additional form for each additional inventor.**

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LEGAL NAME OF INVENTOR

Inventor: TAN, JUAN BOON

Date : 31 OCT 2019

Signature:

**Note: An application data sheet (PTO/SB/14 or equivalent), including naming the entire inventive entity, must accompany this form. Use an additional form for each additional inventor.**

GF Ref. No.: LSG034-US-NP

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LEGAL NAME OF INVENTOR

Inventor: LEONG, CHEE KONG  Date : 29 OCT 2019

Signature: ______________________

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LEGAL NAME OF INVENTOR

Inventor: **RAJOO, RANJAN** Date: 25/10/2019

Signature: Rj

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LEGAL NAME OF INVENTOR

Inventor: RAO, XUESONG

Date : 29/10/2019

Signature: Rao

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GF Ref. No.: LSG034-US-NP

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LEGAL NAME OF INVENTOR

Inventor: **LI, XIAODONG** Date: 31-Oct'19

Signature: ____________

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